Report NO.: M000004000265

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	BSS138W
Package Type :	SOT-323

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.71%
Lead Frame	Copper	7440-50-8	2.00%	26.46%
	Iron	7439-89-6	55.00%	
	Nickel	7440-02-0	41.40%	
	Manganese	7439-96-5	0.80%	
	Silicon	7440-21-3	0.30%	
	Carbon	7440-44-0	0.05%	
	Aluminum	7429-90-5	0.10%	
	Chromium	7440-47-3	0.10%	
	Cobalt	7440-48-4	0.20%	
	Phosphorus	7723-14-0	0.03%	
	Sulphur	7704-34-9	0.03%	
Wire	Copper	7440-50-8	99.99%	0.13%
	Others	/	0.01%	
Mold Compound	Silica	14808-60-7	87.50%	70.08%
	Epoxy Resin	29690-82-2	6.00%	
	Phenol Resin	9003-35-4	6.00%	
	Carbon black	1333-86-4	0.50%	
Plating	Tin	7440-31-5	99.99%	2.62%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.